

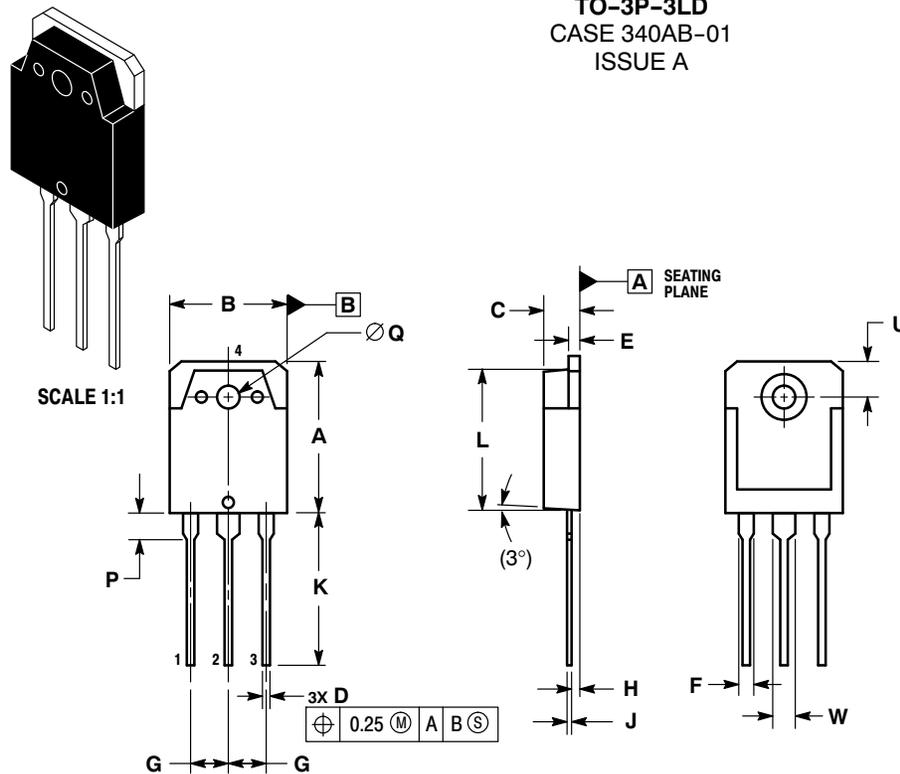
MECHANICAL CASE OUTLINE PACKAGE DIMENSIONS

ON Semiconductor®



TO-3P-3LD CASE 340AB-01 ISSUE A

DATE 30 OCT 2007



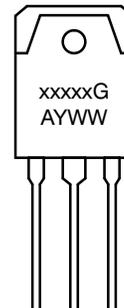
NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS
3. DIMENSION b APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN 0.15 AND 0.30mm FROM THE TERMINAL TIP.
4. DIMENSION A AND B DO NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR GATE BURRS.

MILLIMETERS			
DIM	MIN	NOM	MAX
A	19.70	19.90	20.10
B	15.40	15.60	15.80
C	4.60	4.80	5.00
D	0.80	1.00	1.20
E	1.45	1.50	1.65
F	1.80	2.00	2.20
G	5.45 BSC		
H	1.20	1.40	1.60
J	0.55	0.60	0.75
K	19.80	20.00	20.20
L	18.50	18.70	18.90
P	3.30	3.50	3.70
Q	3.10	3.20	3.50
U	5.00 REF		
W	2.80	3.00	3.20

- | | | |
|--------------|--------------|-------------|
| STYLE 1: | STYLE 2: | STYLE 3: |
| PIN 1. BASE | PIN 1. ANODE | PIN 1. GATE |
| 2. COLLECTOR | 2. CATHODE | 2. DRAIN |
| 3. EMITTER | 3. ANODE | 3. SOURCE |
| 4. COLLECTOR | 4. CATHODE | 4. DRAIN |

GENERIC MARKING DIAGRAM*



- xxxxx = Specific Device Code
- G = Pb-Free Package
- A = Assembly Location
- Y = Year
- WW = Work Week

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G", may or not be present.

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STATUS:	ON SEMICONDUCTOR STANDARD	
NEW STANDARD:		
DESCRIPTION:	TO-3P-3LD	PAGE 1 OF 2

